each of said specified terminal-forming areas including one or more terminal parts therein, said terminal parts being clustered such that those of said terminal parts within a same one of said terminal-forming areas are closer together than those of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

REMARKS

Claims 1, 2, 4, 6 and 7 are currently in the application. Claims 3, 5, 8 and 9 have been withdrawn. Claim 1 is herein being amended.

Claims 1, 2, 4, 6 and 7 were rejected under 35 U.S.C. 102 as being anticipated by Matsui. In Paragraph 5 of the Official Letter, however, the Examiner commented on the earlier presented amendment to claim 1 by saying that the newly introduced limitation was presented in the preamble section, not in the claims structure. In view of this instruction, which is much appreciated by applicant, claim 1 is herein amended for the second time to transfer said additional limitation from the preamble section to the main part of claim 1. It is therefore

believed that said newly introduced limitation will be more favorably considered by the Examiner, leading to the allowance of the application.

Attached hereto is a marked-up version of the changes made to claim 1 by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,

Dated: June 21, 2001

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Version with markings to show changes made

IN THE CLAIMS:

Claim 1 has been amended as follows:

1. (Twice amended) A method of surface-mounting a plurality of electronic components having conductive connecting members ~~to a plurality of specified terminal-forming areas of a target surface having terminal parts therein, said terminal parts being clustered such that those of said terminal parts within a same one of said terminal-forming areas are closer together than those of said terminal parts in different ones of said terminal-forming areas~~, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas including one or more terminal parts therein, said terminal parts being clustered such that those of said terminal parts within a same one of said terminal-forming areas are closer together than those of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.